

ABSTRACT

A cyanate-epoxy resin composition comprising (A) a cyanate type compound containing two or more cyanato groups in one molecule thereof, (B) an epoxy resin, and (C) a curing accelerator, wherein the epoxy resin is derived from a dicyclopentadiene-phenol polyaddition product having a dicyclopentadiene skeleton, and the curing accelerator comprises a combination of a compound having the function to accelerate the curing reaction of the above (A) and a compound having the function to accelerate the curing reaction of the above (B). This cyanate-epoxy resin composition is excellent in glass transition temperature, dielectric characteristics, heat resistance and low susceptibility to water, and can be effectively used for preparing a prepreg and for manufacturing a laminate, a metal foil-laminated plate and a printed wiring board using the prepreg.